

C103 / CW008A is a commercially pure oxygen free copper manufactured by re-melting and pouring in a protective gas atmosphere. The C103 has a minimum copper content of 99.95% and offers an electrical conductivity of greater than 100% IACS (the highest available from commercially pure copper) enabling it's use in electronic applications.

Apart from the increase in thermal and electrical conductivity, the other benefit in the removal of oxygen is that C103 is not susceptible to hydrogen embrittlement when heated in a reducing atmosphere. This enables the Cu-OF alloy to be welded using gas shielded arc, butt and oxy-acetylene methods.

### Chemical Composition

Copper	99.95 min (incl.Ag)
Lead	0.005% max
Bismuth	0.0010% max
Total Imps	0.03% max (excl. O <sub>2</sub> & Ag)

### Related Specifications

- BS2874 / BS1433: C103
- BS EN 13601: CW008A
- C10200
- Cu-OF

### Key Features

- Excellent Conductivity Values
- Freedom From Hydrogen Embrittlement
- Excellent formability
- Excellent Joining Characteristics

### Typical Physical Properties

Melting Point	1083°C
Density	8.9 g/cm <sup>3</sup>
Specific heat	385 J/Kg °K
Thermal conductivity (RT)	393 W/m°K
Thermal expansion coefficient (20-200°C)	17.3 x 10 <sup>-6</sup>
Electrical conductivity	100-101.5% IACS
Electrical Resistivity	0.01724 ohm mm <sup>2</sup> /m

### Fabrication Properties

Hot Working Temperature Range	750-950°C
Hot Formability	Good
Cold Formability	Excellent
Cold reduction between anneals	95% max.
Machinability rating (free cutting brass = 100)	20%
Annealing Temp. Range	200-650°C
Stress Relieving Temp. Range	150-200°C

